

	Type	Hits	Search Text
1	BRS	86013	radio adj frequency
2	BRS	180	radio adj frequency adj component
3	IS&R	1220	(257/690).CCLS.
4	IS&R	651	(257/727).CCLS.
5	IS&R	539	(257/728).CCLS.
6	IS&R	235	(257/660).CCLS.
7	IS&R	753	(257/659).CCLS.
8	IS&R	1163	(257/700).CCLS.
9	BRS	15	((chip with substrate) with ((conductive adj layer) near1 chip))
10	BRS	0	((conductive adj layer adj (inside)) near chip)
11	BRS	98	((conductive adj layer) near chip)
12	BRS	1406	((conductive adj layer) with chip)
13	BRS	0	((conductive adj layer adj in) with chip)
14	BRS	1	((((buried near conductive) adj layer) near (conductive adj layer)) with chip)
15	BRS	17	((buried near conductive) with chip)
16	BRS	397	((chip with substrate) with (conductive adj layer))
17	BRS	369	((chip with substrate) with (conductive adj layer))

	DBs	Time Stamp	Comments	Error Definition
1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:34		
2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:43		
3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 17:50		
4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 16:06		
5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 16:07		
6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 19:22		
7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 18:06		
8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 18:40		
9	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 19:25		
10	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 19:33		
11	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 19:49		
12	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 19:49		
13	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 19:50		
14	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 19:52		
15	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 19:53		
16	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 21:12		
17	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 21:52		

	Errors
1	0
2	0
3	0
4	0
5	0
6	0
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9	0
10	0
11	0
12	0
13	0
14	0
15	0
16	0
17	0

	Type	Hits	Search Text
18	BRS	267	(chip adj (contact or contacts)) with (conductive)
19	BRS	359	(chip adj (contact or contacts)) with (conductive or conductor)
20	BRS	384870	chip
21	BRS	49285	chip with substrate
22	BRS	8779	257/\$.ccls. and (chip with substrate)
23	BRS	2037	257/\$.ccls. and (chip near substrate)
24	BRS	24605	((substrate with (contacts)))
25	BRS	8	(substrate near (buried near conductive near layer))
26	BRS	2392	(substrate near ((mono\$1crystalline) adj (silicon)))
27	BRS	1160	257/\$.ccls. and (substrate near ((mono\$1crystalline) adj (silicon)))
28	BRS	3	257/\$.ccls. and ((substrate near ((mono\$1crystalline) adj (silicon))) with (advantage))
29	BRS	5	((substrate near ((mono\$1crystalline) adj (silicon))) with (advantage))
30	BRS	0	((substrate near ((mono\$1crystalline) adj (silicon))) with (advantage))
31	BRS	9	257/\$.ccls. and (substrate near ((mono\$1crystalline) adj (silicon)))
32	BRS	5	257/\$.ccls. and (substrate with ((mono\$1crystalline) adj (silicon))) with advantage

	DBs	Time Stamp	Comments	Error Definition
18	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 21:53		
19	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 22:33		
20	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 22:34		
21	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 22:35		
22	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 22:35		
23	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 22:38		
24	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 22:39		
25	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 22:53		
26	USPAT	2002/09/14 22:54		
27	USPAT	2002/09/14 23:10		
28	USPAT	2002/09/14 22:57		
29	USPAT	2002/09/14 22:58		
30	JPO	2002/09/14 22:59		
31	JPO	2002/09/14 22:59		
32	USPAT	2002/09/14 23:10		

	Errors
18	0
19	0
20	0
21	0
22	0
23	0
24	0
25	0
26	0
27	0
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29	0
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31	0
32	0